### **SMBus Dual/Quad Current Monitor**

### **General Description**

The MAX34408/MAX34409 are two- and four-channel current monitors that are configured and monitored with a standard I<sup>2</sup>C/SMBus serial interface. Each unidirectional current sensor offers precision high-side operation with a low full-scale sense voltage. The devices automatically sequence through two or four channels and collect the current-sense samples and average them to reduce the effect of impulse noise. The raw ADC samples are compared to user-programmable digital thresholds to indicate overcurrent conditions. Overcurrent conditions trigger a hardware output to provide an immediate indication to shut down any necessary external circuitry.

#### **Applications**

- Network Switches and Routers
- Base Stations
- Servers
- Smart Grid Network Systems
- Industrial Controls

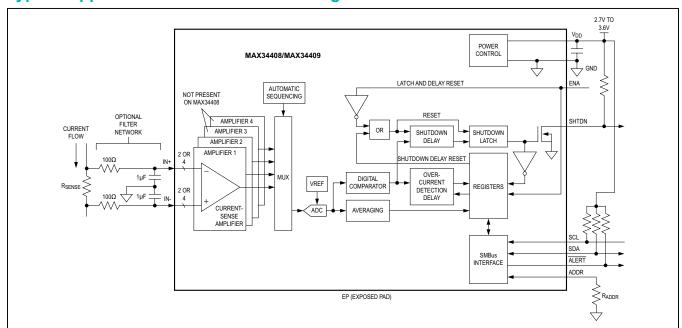
Ordering Information appears at end of data sheet.

#### **Benefits and Features**

- Enables Accurate Current Consumption Measurement on Up to Four Rails with Digital Serial Readout
  - · Low 12.25mV Full-Scale Current-Sense Voltage
  - Automatic Round Robin Sequencing to Sample Each Current-Sense Input
  - Selectable Averaging to Improve Current-Sense Accuracy
  - Programmable Digital Overcurrent Thresholds with Delay Function
  - I<sup>2</sup>C/SMBus Interface with Bus Timeout
  - · Register Access to Real-Time Current Measurements
- Compatible on a Wide Range of Voltage Rails
  - Wide 2.5V to 13.2V Common-Mode Range
- Automatic System Shutdown on Overcurrent Condition
  - Shutdown Output Provides Immediate Hardware Indication of Overcurrent

For related parts and recommended products to use with this part, refer to www.maximintegrated.com/MAX34408.related.

### **Typical Application Circuit and Block Diagram**





### SMBus Dual/Quad Current Monitor

### **Absolute Maximum Ratings**

Voltage Range on V <sub>DD</sub> Relative to GND0.3V to +4V
Voltage Range on IN+, IN- Relative to GND0.3V to +16V
Voltage Range on All Other Pins
Relative to GND0.3V to (V <sub>DD</sub> + 0.3V) (not to exceed +4V)
Differential Input Voltage, IN+ to IN±16V

Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
16-Pin TQFN (derate 25mW/°C above +70°	C)2000mW
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	55°C to +125°C
Soldering Temperature (reflow)	+260°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### Package Thermal Characteristics (Note 1)

#### **TQFN**

Junction-to-Ambient Thermal Resistance ( $\theta_{JA}$ )...........40°C/W Junction-to-Case Thermal Resistance ( $\theta_{JC}$ ).............6°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

## **Recommended DC Operating Conditions**

 $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C.) \text{ (Notes 2, 3)}$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP MAX	UNITS
V <sub>DD</sub> Operating Voltage Range	V <sub>DD</sub>		2.7	3.6	V
Input Logic 1: ENA Pin	V <sub>IH1</sub>		V <sub>DD</sub> x 0.7	V <sub>DD</sub> + 0.3	V
Input Logic 0: ENA Pin	V <sub>IL1</sub>		-0.3	+0.3 x V <sub>DD</sub>	V
Input Logic 1: SCL/SDA Pins	V <sub>IH2</sub>		2.1	V <sub>DD</sub> + 0.3	V
Input Logic 0: SCL/SDA Pins	V <sub>IL2</sub>		-0.3	+0.8	V

#### **Electrical Characteristics**

 $(V_{IN+} = V_{IN-} = 12V, V_{SENSE} = 0V, V_{DD} = 2.7V \text{ to } 3.6V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DD} = 3.3V \text{ and } T_A = +25^{\circ}\text{C}.) \text{ (Notes 2, 3)}$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current	I <sub>DD</sub>	SMBus idle		830		μA
Current-Sense Common-Mode Input Range			2.5		13.2	V
Input Bias Current (IN+/IN-)		Common-mode voltage = 13.2V, IN input differential = 12.25mV		2		μA
ADC Resolution			8			Bits
Per-Channel Current Sample Rate				1		ksps
IN Input Full Scale			12.00	12.25	12.50	mV
ADC INL				±0.5	±2	LSB
ADC DNL				±0.5	±2	LSB
IN Input Offset				±0.5	±4	LSB

### **Electrical Characteristics (continued)**

 $(V_{IN+} = V_{IN-} = 12V, V_{SENSE} = 0V, V_{DD} = 2.7V \text{ to } 3.6V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$  Typical values are at  $V_{DD} = 3.3V$  and  $T_A = +25^{\circ}\text{C}$ .) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Logic Low (SHTDN, ALERT)	V <sub>OL</sub>	I <sub>OL</sub> = 4mA			0.4	V
Output Leakage (SHTDN, ALERT)					±1	μA
SCL, SDA Leakage		V <sub>DD</sub> = 0V or float			±5	μA
ENA Leakage					±1	μA
Digital Comparator Resolution			8			Bits
Delay Time from V <sub>DD</sub> Applied Until SMBus Active (Figure 1)	<sup>t</sup> SMBD			500		μs
Delay Time from Common-Mode Voltage Applied Until Current Monitoring Active (Figure 1)	<sup>t</sup> CSAD			10		ms

### AC Electrical Characteristics: I2C/SMBus Interface

 $(V_{DD}$  = 2.7V to 3.6V,  $T_A$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $V_{DD}$  = 3.3V,  $T_A$  = +25°C.) (Notes 3, 4) (Figure 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCL Clock Frequency	f <sub>SCL</sub>		10		400	kHz
Bus Free Time Between STOP and START Conditions	t <sub>BUF</sub>		1.3			μs
Hold Time (Repeated) START Condition	t <sub>HD:STA</sub>		0.6			μs
Low Period of SCL	t <sub>LOW</sub>		1.3			μs
High Period of SCL	tHIGH		0.6			μs
Data Hold Time		Receive	0			200
Data Hold Time	<sup>t</sup> HD:DAT	Transmit	300			ns
Data Setup Time	t <sub>SU:DAT</sub>		100			ns
Start Setup Time	t <sub>SU:STA</sub>		0.6			μs
SDA and SCL Rise Time	t <sub>R</sub>				300	ns
SDA and SCL Fall Time	t <sub>F</sub>				300	ns
Stop Setup Time	t <sub>SU:STO</sub>		0.6	·		μs
Clock Low Timeout	t <sub>TO</sub>		25		35	ms

**Note 2:** All voltages are referenced to ground. Current entering the device are specified as positive and currents exiting the device are negative.

Note 3: Limits are 100% production tested at  $T_A = +25$ °C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.

Note 4: All timing specifications are guaranteed by design.

# **Timing Diagrams**

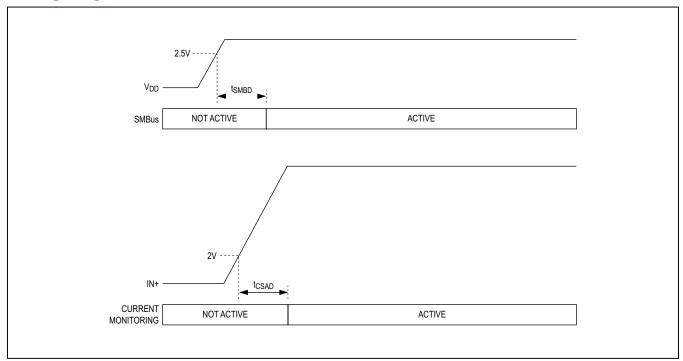


Figure 1. Delay Timing

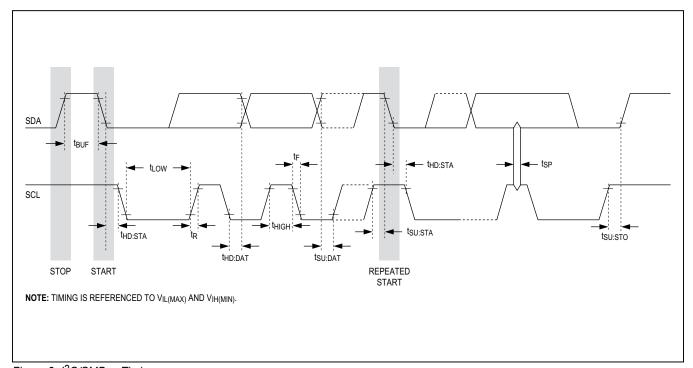
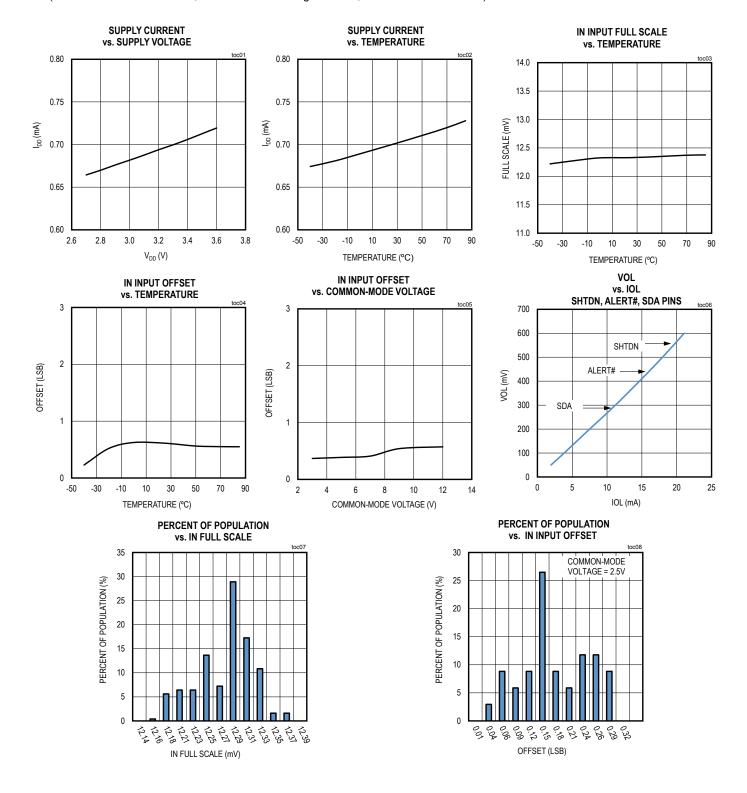


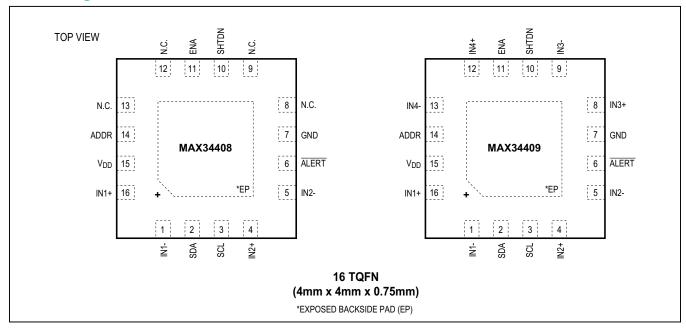
Figure 2. I<sup>2</sup>C/SMBus Timing

## **Typical Operating Characteristics**

(V<sub>DD</sub> = 3.3V and T<sub>A</sub> = +25°C, common-mode voltage = 12.0V, unless otherwise noted.)



# **Pin Configurations**



## **Pin Description**

PIN MAX34408 MAX34409		NAME	FUNCTION	
		NAME	FUNCTION	
1	1	IN1-	External Sense Resistor Load-Side Connection for Amplifier 1. This pin should be left open circuit if not needed.	
2	2	SDA	I <sup>2</sup> C/SMBus-Compatible Data Input/Output. Output is open drain.	
3	3	SCL	I <sup>2</sup> C/SMBus-Compatible Clock Input	
4	4	IN2+	External Sense Resistor Power-Side Connection for Amplifier 2. This pin should be left open circuit if not needed.	
5	5 5 IN2-		External Sense Resistor Load-Side Connection for Amplifier 2. This pin should be left open circuit if not needed.	
6	6	ALERT	I <sup>2</sup> C/SMBus Interrupt. Open-drain output.	
7	7	GND	Ground Connection	
8, 9, 12, 13	_	N.C.	No Connection. Do not connect any signal to this pin.	
10	10	SHTDN	Shutdown Output. Open-drain output. This output transitions to high impedance when any of the digital comparator thresholds are exceeded as long as the ENA pin is high.	
11	11 11 ENA		SHTDN Enable Input. CMOS digital input. Connect to GND to clear the latch and unconditionally deassert (force low) the SHTDN output and reset the shutdown delay. Connect to V <sub>DD</sub> to enable normal latch operation of the SHTDN output.	
14 14 ADDR ground to determine the 7-bit s		ADDR	I <sup>2</sup> C/SMBus Address Select. On device power-up, the device samples a resistor to ground to determine the 7-bit serial bus address. See the <i>Addressing</i> section for details on which resistor values select which SMBus address.	

### **Pin Description (continued)**

PIN		NAME	FUNCTION
MAX34408	MAX34409	NAME	FUNCTION
15	15	V <sub>DD</sub>	Supply Voltage for Comparators and Logic. A +2.7V to +3.6V supply. This pin should be decoupled to GND with a 100nF ceramic capacitor.
16	16	IN1+	External Sense Resistor Power-Side Connection for Amplifier 1. This pin should be left open circuit if not needed.
_ 8		IN3+	External Sense Resistor Power-Side Connection for Amplifier 3. This pin should be left open circuit if not needed.
_	9	IN3-	External Sense Resistor Load-Side Connection for Amplifier 3. This pin should be left open circuit if not needed.
_ 12		IN4+	External Sense Resistor Power-Side Connection for Amplifier 4. This pin should be left open circuit if not needed.
_ 13		IN4-	External Sense Resistor Load-Side Connection for Amplifier 4. This pin should be left open circuit if not needed.
— — EP Exposed		EP	Exposed Pad. No internal electrical connection. Can be left open circuit.

### **Detailed Description**

The MAX34408 and MAX34409 are two- and four-channel current monitors that are configured and monitored with a standard I<sup>2</sup>C/SMBus serial interface. Each unidirectional current sensor offers precision high-side operation with a low full-scale sense voltage. The devices automatically sequence through two or four channels and collect the current-sense samples and average them to reduce the effect of impulse noise. The raw ADC samples are compared to user-programmable digital thresholds to indicate overcurrent conditions. Overcurrent conditions trigger a hardware output to provide an immediate indication to shut down any necessary external circuitry.

The devices provide an ALERT output signal. Host communications are conducted through a SMBus-compatible communications port.

#### **SMBus Operation**

The devices use the SMBus command/response format as described in the System Management Bus Specification Version 2.0. The structure of the data flow between the host and the slave is shown for several different types of transactions. Data is sent MSB first. The fixed slave address of the MAX34408 or MAX34409 is determined on device power-up by sampling the resistor connected to the ADDR pin. See the <u>Addressing</u> section for details. On device power-up, the device defaults to the STATUS command code (00h). If the host sends an invalid command code, the device NACKs (not acknowledge) the command code. If the host attempts to read the device with an invalid command code, all ones (FFh) are returned in the data byte.

#### **Table 1. Read Byte Format**

1	7	1	1	8	1	1	7	1	1	8	1	1
S	Slave Address	W	А	Command Code	А	SR	Slave Address	R	Α	Data Byte	NA	Р

### **Table 2. Write Byte Format**

1	7	1	1	8	1	8	1	1
S	Slave Address	w	А	Command Code	Α	Data Byte	А	Р

#### Key:

S = Start

SR = Repeated Start

P = Stop

W = Write Bit (0)

R = Read Bit (1)

A = Acknowledge (ACK) (0)

NA = Not Acknowledge (NACK) (1)

Shaded Block = Slave Transaction

#### Addressing

The devices respond to receiving the fixed slave address by asserting an ACK on the bus. The fixed slave address of the MAX34408 or MAX34409 is determined on device power-up by sampling the resistor connected to the ADDR pin. See Table 4 for more details. The devices do not respond to a General Call address, only when it receives its fixed slave address or the Alert Response Address (ARA). See the ALERT description for more details.

#### **ALERT and Alert Response Address (ARA)**

If the  $\overline{ALERT}$  output is enabled (ALERT bit = 1 in CONTROL), when an overcurrent condition is detected, the devices assert the ALERT signal and then wait for the host to send the Alert Response Address (ARA) as shown in Table 5.

When the ARA is received and the devices are asserting ALERT, the devices attempt to place the fixed slave

### Table 3. Receive Byte Format (reads data from the last transacted command code)

1	7	1	1	8	1	1
S	Slave Address	R	Α	Data Byte	NA	Р

#### Table 4. SMBus Slave Address Select

R <sub>ADDR</sub> (±1%)	SLAVE ADDRESS	R <sub>ADDR</sub> (±1%)	SLAVE ADDRESS
Open	0011 110 (3Ch)	3.01kΩ	0010 110 (2Ch)
9.31kΩ	0011 100 (38h)	1.69kΩ	0010 100 (28h)
6.81kΩ	0011 010 (34h)	750Ω	0010 010 (24h)
4.75kΩ	0011 000 (30h)	0 (connect to GND)	0010 000 (20h)

### Table 5. Alert Response Address (ARA) **Byte Format**



address on the bus by arbitrating the bus since another device may also try to respond to the ARA. The rules of arbitration state that the lowest address device wins. If the devices win the arbitration, they deassert ALERT. If the devices lose arbitration, they keep ALERT asserted and wait for the host to once again send the ARA.

#### **SMBus Commands**

A summary of the SMBus commands supported by the devices are described in the following sections, see  $\underline{\text{Table 6}}$ .

**Table 6. Command Codes** 

COMMAND CODE	NAME	DETAILED DESCRIPTION	TYPE	POR (Note 1)
00h	STATUS	Overcurrent Alarm	R/W Byte	00h
01h	CONTROL	Device Configuration	R/W Byte	0Ch
02h	OCDELAY	Overcurrent Detection Delay Configuration	R/W Byte	04h
03h	SDDELAY	SHTDN Pin Delay Configuration	R/W Byte	14h
04h	ADC1	Averaged ADC Reading from Current Sensor 1	Read Byte	_
05h	ADC2	Averaged ADC Reading from Current Sensor 2	Read Byte	_
06h	ADC3	Averaged ADC Reading from Current Sensor 3 (Note 2)	Read Byte	_
07h	ADC4	Averaged ADC Reading from Current Sensor 4 (Note 2)	Read Byte	_
08h	OCT1	Overcurrent Threshold for Current Sensor 1	R/W Byte	D1h
09h	OCT2	Overcurrent Threshold for Current Sensor 2	R/W Byte	D1h
0Ah	ОСТ3	Overcurrent Threshold for Current Sensor 3 (Note 3)	R/W Byte	D1h
0Bh	OCT4	Overcurrent Threshold for Current Sensor 4 (Note 3)	R/W Byte	D1h
0Ch	DID	Device ID & Revision	Read Byte	Factory Set
0Dh	DCYY	Date Code Year	Read Byte	Factory Set
0Eh	DCWW	Date Code Work Week	Read Byte	Factory Set

**Note 1:** POR = Power-on reset, and this is the default value when power is applied to the device.

Note 2: In the MAX34408, ADC3 and ADC4 always report 00h when read.

Note 3: In the MAX34408, OCT3 and OCT4 can be written to and read from, but they have no affect on the device.

#### STATUS (00h)

The STATUS command returns 1 byte of information with a summary of the fault conditions along with the real-time status of the ENA and SHTDN pins. The STATUS byte message content is described in <u>Table 7</u>. See <u>Figure 3</u> for STATUS bits 3:0 organization.

Table 7. STATUS (00h)—R/W Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	NA	NA	ENA	SHTDN	OC4	OC3	OC2	OC1
POR	0	0	0	0	0	0	0	0

Note: Bit positions marked as NA are Not Assigned and have no meaning. These bits can be either 0 or 1 when read.

BIT	NAME	DESCRIPTION
5	ENA	This bit reports the real-time status of the ENA input pin. The ENA pin is sampled when SMBus communication is initiated. This bit has no affect on the ALERT output. Writing a 0 or 1 to this bit position has no affect on the device.
4	SHTDN	This bit reports the real-time status of the SHTDN output pin. The shutdown latch is sampled when SMBus communication is initiated. This bit has no affect on the ALERT output. Writing a 0 or 1 to this bit position has no affect on the device.
3:0	OC4/OC3/ OC2/OC1 (MAX34409)	These bits reflect the latched status of the overcurrent thresholds for each current sensor. The OCD0 to OCD3 bits configured with the OCDELAY command determine the number of consecutive overcurrent threshold excursion samples that are required to set these bits. Once set, these bits remain set until written with a 0. Once they are cleared, they are not set again until the sensed
1:0 OC2/OC1 (MAX34408		current has exceeded the threshold for the programmed delay time. The setting of any of these bits asserts the ALERT pin if the ALERT bit in the CONTROL command is set to a one. Reading or writing the STATUS command deasserts the ALERT pin if it is asserted. In the MAX34408, bit positions OC3 and OC4 are inactive.

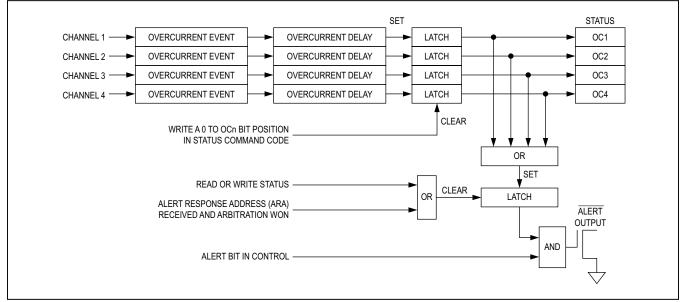


Figure 3. OCn Status Bits Set/Clear Functionality and ALERT Assertion

### CONTROL (01h)

The CONTROL command configures the digital current-sensing averaging function. The CONTROL command also defines if the devices respond to the Alert Response Address. The CONTROL byte command is described in <u>Table 8</u>.

Table 8. CONTROL (01h)—R/W Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	NA	NA	NA	NA	ALERT	AVG2	AVG1	AVG0
POR	0	0	0	0	1	1	0	0

Note: Bit positions marked as NA are Not Assigned and have no meaning. These bits can be either 0 or 1 when read.

BIT	NAME				DESCRIPTION					
3	ALERT		If this bit is cleared, the ALERT output is disabled and the devices do not respond to the Alert Response Address. If this bit is set, the ALERT function is enabled and the devices respond to the Alert Response Address.							
		These bits configure the digital current-sensing averaging function as shown below.								
		AVG2	AVG1	AVG0	SELECTED AVERAGING					
		0	0	0	1 Sample (no averaging)					
		0	0	1	2 Samples					
2:0	AVG2/	0	1	0	4 Samples					
2.0	AVG1/AVG0	0	1	1	8 Samples					
		1	0	0	16 Samples (default)					
		1 0		1	32 Samples					
		1	1	0	64 Samples					
		1	1	1	128 Samples					

### OVER\_CURRENT\_DELAY (02h)

The OVER\_CURRENT\_DELAY command configures and resets the overcurrent delay counters. The OVER\_CURRENT\_DELAY byte command is described in <u>Table 9</u>. See <u>Figure 4</u> for delay counter timing.

Table 9. OVER\_CURRENT\_DELAY (02h)—R/W Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	RESET	OCD6	OCD5	OCD4	OCD3	OCD2	OCD1	OCD0
POR	0	0	0	0	0	1	0	0

BIT	NAME		DESCRIPTION						
7	RESET	If this bit is cleared, the OCD0 to OCD6 bits are used to set the overcurrent delay for all channels. If this is set, all of the overcurrent delay counters are reset and the devices do not trigger any overcurrent events and the OC status bits are cleared.							
		threshold must be continuously the respective OC bit in the ST, with the ALERT bit in the CONT bit and the ALERT output are a	nese bits configure the overcurrent delay as shown below. For each channel, the digital of reshold must be continuously breached in consecutive samples for the delay listed below the respective OC bit in the STATUS register is set and the ALERT output is asserted (if end the ALERT bit in the CONTROL command). For example, if the delay is set to 0ms, the and the ALERT output are asserted on the first sample that breaches the threshold. If does not be the occurrent the consecutive samples.						
		OCD[6:0]	OVERCURRENT DELAY						
		00h	0ms	1 Event					
6:0	OCD6 to OCD0	01h	1ms	2 Consecutive Events					
	OCDU	02h	2ms	3 Consecutive Events					
		03h	3ms	4 Consecutive Events					
		04h	4ms (default)	5 Consecutive Events					
		14h	20ms	21 Consecutive Events					
		15h	21ms	22 Consecutive Events					
		7Eh	126ms	127 Consecutive Events					
	7Fh 127ms 128 Consecutive E								

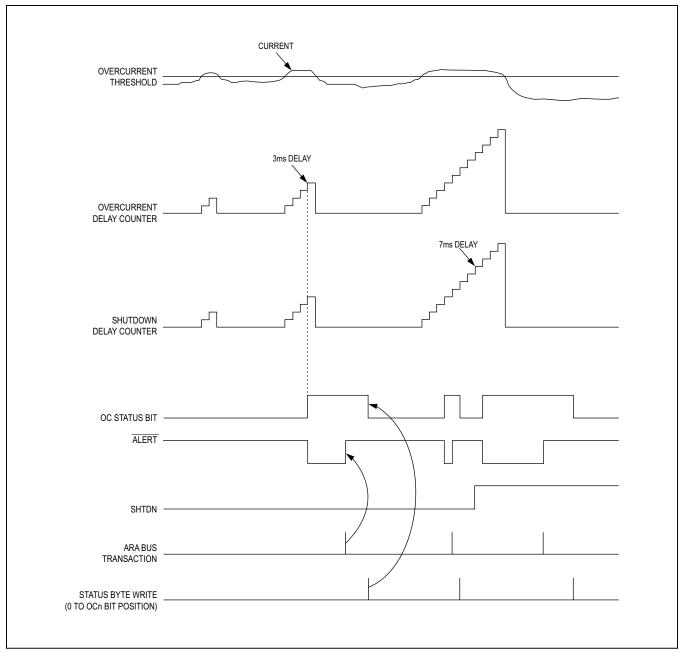


Figure 4. Delay Timing

### SHUTDOWN\_DELAY (03h)

The SHUTDOWN\_DELAY command configures and resets the shutdown delay counters. The SHUTDOWN\_DELAY byte command is described in Table 10.

Table 10. SHUTDOWN\_DELAY (03h)—R/W Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	RESET	SHD6	SHD5	SHD4	SHD3	SHD2	SHD1	SHD0
POR	0	0	0	1	0	1	0	0

BIT	NAME		DESCRIPTION					
7	RESET	If this bit is cleared, the SHD0 to SHD6 bits are used to set the shutdown delay that is used to control the SHTDN pin. If this is set, the shutdown delay counter is reset and the SHTDN pin is forced inactive (low).						
		overcurrent threshold must be of below before the shutdown late is set to 0ms, then the SHTDN	own latch delay as shown below. For continuously breached in consecutive the (and hence the SHTDN pin) is assoutput is asserted on the first sample SHTDN output is not asserted untilemples.	e samples for the delay listed serted. For example, if the delay e that breaches the threshold.				
		SHD[6:0]	SHD[6:0] SHUTDOWN DELAY					
	OLIDO (	00h	0ms	1 Event				
6:0	SHD6 to SHD0	01h	1ms	2 Consecutive Events				
	SIIDO	02h	2ms	3 Consecutive Events				
		03h	3ms	4 Consecutive Events				
		13h	19ms	20 Consecutive Events				
		14h	20ms (default)	21 Consecutive Events				
		15h	21ms	22 Consecutive Events				
		7Eh	126ms	127 Consecutive Events				
		7Fh	127ms	128 Consecutive Events				

#### ADC1/2/3/4 (04h/05h/06h/07h)

The ADC1/2/3/4 command returns the associated latest measured current reading. The ADC1/2/3/4 byte command is described in <u>Table 11</u>.

Table 11. ADC1/2/3/4 (04h/05h/06h/07h)—Read Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	C7	C6	C5	C4	C3	C2	C1	C0
POR	Х	Х	Х	Х	Х	Х	Х	Х

BIT	NAME	DESCRIPTION
7:0	C7 to C0	These bits report the latest current reading from the ADC. The reported results are averaged according to the averaging function as configured with the AVG0 to AVG2 bits in the CONTROL command. Reading the ADC results faster than they are sampled and averaged results in the previous values being reported. In the MAX34408, ADC3 and ADC4 always report 00h when read.

### OVER\_CURRENT\_THRESHOLD\_1/2/3/4 (08h/09h/0Ah/0Bh)

The OVER\_CURRENT\_THRESHOLD\_1/2/3/4 command sets the overcurrent threshold for each channel. The OVER\_CURRENT\_THRESHOLD\_1/2/3/4 byte command is described in  $\underline{\text{Table 12}}$ . See  $\underline{\text{Table 13}}$  for the configuration formula and Table 14 for an example.

### Table 12. OVER\_CURRENT\_THRESHOLD\_1/2/3/4 (08h/09h/0Ah/0Bh)—R/W Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	OCT7	ОСТ6	OCT5	OCT4	ОСТ3	OCT2	OCT1	OCT0
POR	1	1	0	1	0	0	0	1

Note: In the MAX34408, OCT3 and OCT4 can be written to and read from but they have no affect on the device.

BIT	NAME	DESCRIPTION
7:0	OCT7 to OCT0	These bits select the digital overcurrent threshold for each channel. The formula for selecting the threshold is as shown in Table 13. If the threshold is set to FFh, the digital comparator is disabled and the output of the comparator is unconditionally deasserted.

#### **Table 13. Overcurrent Threshold Register Configuration Formula**

Overcurrent Threshold Analog Voltage at the IN+/IN- Pins	÷ 0.01225	= Ratio to Full Scale	x 256	Rounded Decimal Value	=	Overcurrent Threshold Register Setting
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### **Table 14. Overcurrent Threshold Register Example**

10mV	÷	0.01225	II	0.816	Х	256	=	209	=	D1h

#### DEVICE\_ID\_&\_REVISION (0Ch)

The DEVICE\_ID\_&\_REVISION command returns a fixed device ID and a factory programmed revision. The DEVICE\_ID\_&\_REVISION byte command is described in <a href="mailto:Table 15">Table 15</a>.

#### Table 15. DEVICE ID & REVISION (0Ch)—Read Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	ID4	ID3	ID2	ID1	ID0	REV2	REV1	REV0
POR	0	0	0	0	1		Factory set	

BIT	NAME	DESCRIPTION
7:3	ID4 to ID0	These bits report the device identification (ID). The ID is fixed at 01h.
2:0	REV2 to REV0	These bits report the device revision. The device revision is factory set.

### DATE\_CODE\_YEAR (0Dh)

The DATE\_CODE\_YEAR command returns a factory programmed date code. The DATE\_CODE\_YEAR byte command is described in Table 16.

### Table 16. DATE\_CODE\_YEAR (0Dh)—Read Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	0	0	YY5	YY4	YY3	YY2	YY1	YY0
POR	Factory Set							

BIT	NAME	DESCRIPTION					
		These bits report the last two decimal digits of the calendar year in which the device was tested. The year is reported as a binary decimal. Some examples are listed below. The range is valid until the year 2063.					
5:0	YY5 to YY0	YY[5:0]	YEAR				
		0Ch	2012				
		0Dh	2013				
		14h	2020				

#### DATE\_CODE\_WORK\_WEEK (0Eh)

The DATE\_CODE\_WORK\_WEEK command returns a factory-programmed date code. The DATE\_CODE\_WORK\_WEEK byte command is described in Table 17.

### Table 17. DATE\_CODE\_WORK\_WEEK (0Eh)—Read Byte

BIT	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME	0	0	WW5	WW4	WW3	WW2	WW1	WW0
POR	Factory Set							

BIT	NAME	DESCRIPTION						
		These bits report the calendar work week in which the device was tested. The work week is reported as a binary decimal. Some examples are listed below. 00h (0 decimal) and 36h (54 decimal) through 3Fh (63) are not valid.						
5:0	WW5 to WW0	WW[5:0]	WORK WEEK					
	11110	06h	6					
		0Dh	13					
		2Bh	43					

### **Applications Information**

### Sense Resistor, R<sub>SENSE</sub>

Adjust the R<sub>SENSE</sub> value to monitor higher or lower current levels. Select R<sub>SENSE</sub> based on the following criteria:

**Resistor Value:** Select an R<sub>SENSE</sub> resistor value in which the largest expected current results in a 10mV full-scale current-sense voltage. Select R<sub>SENSE</sub> in accordance to the following equation and see Table 18 for examples:

R<sub>SENSE</sub> = 10mV/(Max Current)

**Power Dissipation:** Select a sense resistor that is rated for the max expected current and power dissipation (wattage). The sense resistor's value might drift if it is allowed to heat up excessively.

#### **Accuracy**

Current measurement accuracy increases the closer the measured current readings are to the 12.25mV full-scale current-sense voltage. This is because offsets become less significant when the sense voltage is larger. For best performance, select R<sub>SENSE</sub> to provide approximately 10mV of sense voltage for the full-scale current in each application. Figure 5 shows the error contributed by the input offset vs. reading percentage of full scale.

#### **Table 18. RSENSE Example Values**

R <sub>SENSE</sub> (mΩ)	MAX CURRENT (A)
0.25	40
0.5	20
1	10
5	2
10	1
50	0.2
100	0.1
200	0.05
500	0.02

#### **Kelvin Connections**

Because of the high currents that flow through R<sub>SENSE</sub>, take care to eliminate parasitic trace resistance from causing errors in the sense voltage. Use Kelvin (force and sense) PCB layout techniques as shown in Figure 6.

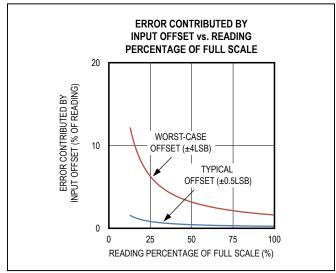


Figure 5. Input Offset Error

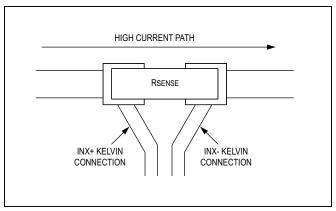


Figure 6. Kelvin Connection Layout Example

#### **Optional Filter Network**

For noisy environments, a simple lowpass filter can be placed at the devices' amplifier inputs as shown in Figure 7. The  $100\Omega$  resistor and  $1\mu\text{F}$  capacitor provide a 1.6kHz rolloff frequency. To achieve the most effective results, use the filter in conjunction with the device's digital averaging as described in the *CONTROL* (01h) section.

#### **Layout Considerations**

For noisy digital environments, the use of a multilayer PCB with separate ground and power-supply planes is recommended. Keep digital signals far away from the sensitive analog inputs. Unshielded long traces at the input terminals of the amplifier can degrade performance due to noise pickup. The analog differential current-sense traces should be routed close together to maximize common-mode rejection.

#### **Power-Supply Decoupling**

To achieve the best results when using these devices, decouple the  $V_{DD}$  power supply with a  $0.1\mu F$  capacitor. Use a high-quality, ceramic, surface-mount capacitor if possible. Surface-mount components minimize lead inductance, which improves performance, and ceramic capacitors tend to have adequate high-frequency response for decoupling applications.

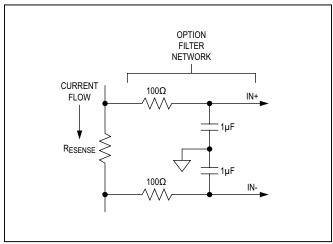


Figure 7. Filter Network

### **Ordering Information**

PART	CONFIGURATION	PIN-PACKAGE
MAX34408ETE+	Dual	16 TQFN-EP*
MAX34409ETE+	Quad	16 TQFN-EP*

<sup>+</sup>Denotes a lead (Pb)-free/RoHS-compliant package.

### **Package Information**

For the latest package outline information and land patterns (foot-prints), go to <a href="www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
16 TQFN-EP	T1644+4	21-0139	90-0070

<sup>\*</sup>EP = Exposed pad.

### MAX34408/MAX34409

## SMBus Dual/Quad Current Monitor

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	9/13	Initial release	_
1	1/15	Updated Benefits and Features section	1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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